

## PRODUCT / PROCESS CHANGE NOTIFICATION

### 1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.		MDG/22/13697
1.3 Title of PCN		VFQFPN32 – Package upgrade for ST33TPHF20, ST33TPHF2E, ST33TPHF2X cancellation
1.4 Product Category		ST33TPHF20, ST33TPHF2E, ST33TPHF2X
1.5 Issue date		2022-10-11

### 2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Marie-France FLORENTIN
2.1.2 Marketing Manager	Denis FARISON
2.1.3 Quality Manager	Mickael DENAIS-ALLICHON

### 3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
General Product & Design	(Not Defined)	AMKOR ATP3

### 4. Description of change

	Old	New
4.1 Description	Warning: This PCN replaces PCN 13417 - VFQFPN32 – Package upgrade for ST33TPHF20, ST33TPHF2E, ST33TPHF2X to support Ultra Low Alpha molding resin to improve Soft Error Rate	The change of the package BOM is cancelled. The list of impacted products initially present in PCN 13417 below will NOT be migrated to a new package. They will be produced with the already qualified package including standard resin.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	Impact on function	

### 5. Reason / motivation for change

5.1 Motivation	The cancellation of the package change is due to strategic choices to increase the reliability of the supply chain.
5.2 Customer Benefit	SERVICE CONTINUITY

### 6. Marking of parts / traceability of change

6.1 Description	For each Commercial Product impacted by the change, a new Finished Good codification will be created. This Finished Good codification is present on the label.
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### 7. Timing / schedule

7.1 Date of qualification results	2022-09-30
7.2 Intended start of delivery	2022-10-07
7.3 Qualification sample available?	Not Applicable

### 8. Qualification / Validation

8.1 Description		
8.2 Qualification report and qualification results	In progress	Issue Date

**9. Attachments (additional documentations)**

13697 Public product.pdf  
13697 PCN TPM VFQFPN32 - Package change cancellation v1.0.pdf

**10. Affected parts**

<b>10. 1 Current</b>		<b>10.2 New (if applicable)</b>
<b>10.1.1 Customer Part No</b>	<b>10.1.2 Supplier Part No</b>	<b>10.1.2 Supplier Part No</b>
	ST33HTPH2032AHD1	

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### TPM VFQFPN32 – Package upgrade cancellation

#### VFQFPN32 – Package upgrade for ST33TPHF20, ST33TPHF2E, ST33TPHF2X cancellation

**Warning:** This PCN replaces **PCN 13417** - VFQFPN32 – Package upgrade for ST33TPHF20, ST33TPHF2E, ST33TPHF2X to support Ultra Low Alpha molding resin to improve Soft Error Rate

#### What are the changes?

The change of the package BOM is cancelled. The list of impacted products initially present in PCN 13417 below will NOT be migrated to a new package. They will be produced with the already qualified package including standard resin.

Commercial Product	Finished Good BOM with standard resin	Finished Good CANCELED (BOM with ULA resin)
ST33HTPH2E32AHA5	33HTPH2E32CHB2CT	33HTPH2E32CHB2CU
ST33HTPH2032AAF3	33HTPH2032CHA3CT	33HTPH2032CHA3CU
ST33HTPH2032GAF3	OIMMY8K42P00875	TBD
ST33HTPH2E32AHB4	33HTPH2E32CHB4CT	33HTPH2E32CHB4CU
ST33HTPH2E32AHC2	33HTPH32CHD2CT	33HTPH32CHD2CU
ST33HTPH2032AHC3	33HTPH32CHD3CT	33HTPH32CHD3CU
ST33HTPH2E32AHD0	33HTPH32CHD0CT	33HTPH32CHD0CU
ST33HTPH2032AHD1	33HTPH32CHD1CT	33HTPH32CHD1CU
ST33HTPH2X32AHD4	33HTPH32CHD4CT	33HTPH32CHD4CU
ST33HTPH2X32AHD5	33HTPH32CHD5CT	33HTPH32CHD5CU
ST33HTPH2E32AHD6	33HTPH32CHD6CT	33HTPH32CHD6CU
ST33HTPH2032AHD7	33HTPH32CHD7CT	33HTPH32CHD7CU
ST33HTPH2X32AHD8	33HTPH32CHD8CT	33HTPH32CHD8CU
ST33HTPH2X32AHE0	33HTPH32CHE0CT	33HTPH32CHE0CU
ST33HTPH2X32AHE1	33HTPH32CHE1CT	33HTPH32CHE1CU
ST33HTPH2X32AHE4	33HTPH32CHE4CT	33HTPH32CHE4CU

#### Why?

The cancellation of the package change is due to strategic choices to increase the reliability of the supply chain.

#### When?

There is no plan to change the package on the long term.

#### How will the change be qualified?

Not applicable.

## Document Revision History

Date	Rev.	Description of the Revision
29/Sep/2022	1.0	First release



## Public Products List

Public Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

**PCN Title :** VFQFPN32 – Package upgrade for ST33TPHF20, ST33TPHF2E, ST33TPHF2X cancellation

**PCN Reference :** MDG/22/13697

**Subject :** Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

ST33HTPH2X32AHD8	ST33HTPH2E32AHC2	ST33HTPH2X32AHD4
ST33HTPH2E32AHD0	ST33HTPH2X32AHD5	ST33HTPH2032AHC3
ST33HTPH2032AHD1		



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